



PCB Design for the Real World

Using OrCAD X with Solidworks to codesign your next electronic product

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Electrification of Everything

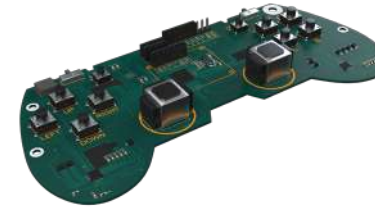
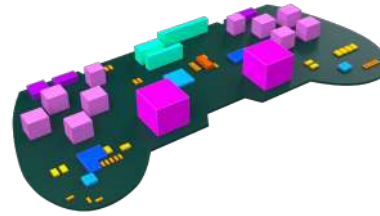
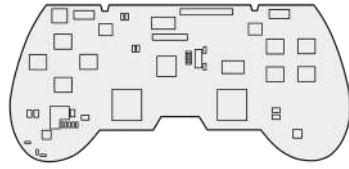
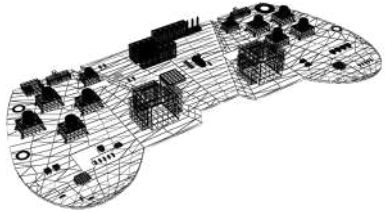
- Electronic and mechanical systems are highly interdependent

- Challenges/Issues

- Interference
- Thermal Management
- Manufacturing
- Communication



Migration & Limitations of MCAD/ECAD Exchange

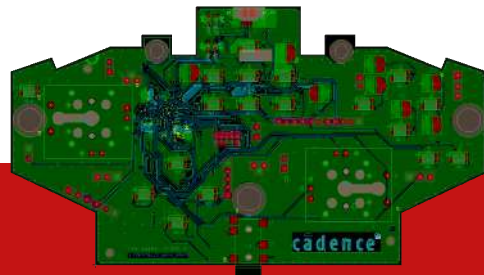


Great at Capturing Mechanical Intent		Incorporation of Electronic Intent			
<p>IGES</p> <ul style="list-style-type: none"> • Surface model representation • Origin: USAF • Initial release: 1978 • Last update: 1996 • V 5.3 – last version 	<p>DXF</p> <ul style="list-style-type: none"> • 2D vectorized line format • Origin: Autodesk • Initial release: 1982 • Last update: 2007 • V u19.1.01 	<p>IDF</p> <ul style="list-style-type: none"> • 2D with 3rd dimension a property value • Origin: Mentor Graphics • Initial release: 1992 • Last update: 1998 • V 4.0 – continues to evolve 	<p>STEP</p> <ul style="list-style-type: none"> • Single solid model representation • Origin: ISO • Initial release: 1995 (AP203) • Last update: 2016 • V AP242 	<p>IDX</p> <ul style="list-style-type: none"> • Best of STEP & IDF with incremental change support • Origin: ProSTEP • Initial release: 2010 • Last update: 2022 • V 5.0 	
1978	1982	1992	1995	2010	2024

No management of transactions or traceability

Harmonizing MCAD/ECAD Data Exchange & Management

- Blue Text: Single direction transfer from ECAD to MCAD
- Red Text: Bi-directional transfer between ECAD & MCAD



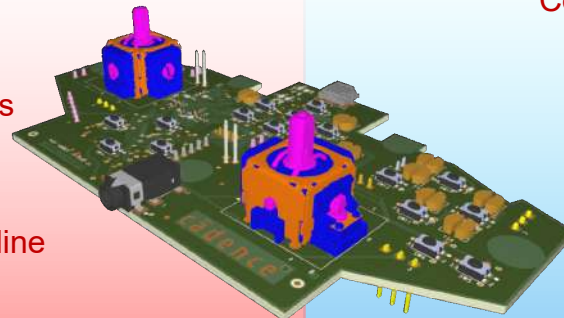
- Initial clearance checks
- Electrical integrity
- Functional verification
- PCB manufacturing
- Allegro X AI

Copper Traces & Shapes

Plated & Unplated Holes

Board Outline

Keep In, Keep Out Regions



IDX

Accept, Reject, Revert



3DEXPERIENCE

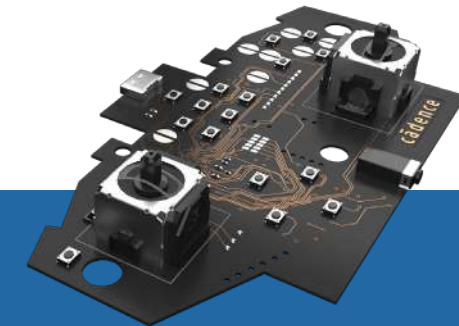
Component Name & Designator

Board Thickness

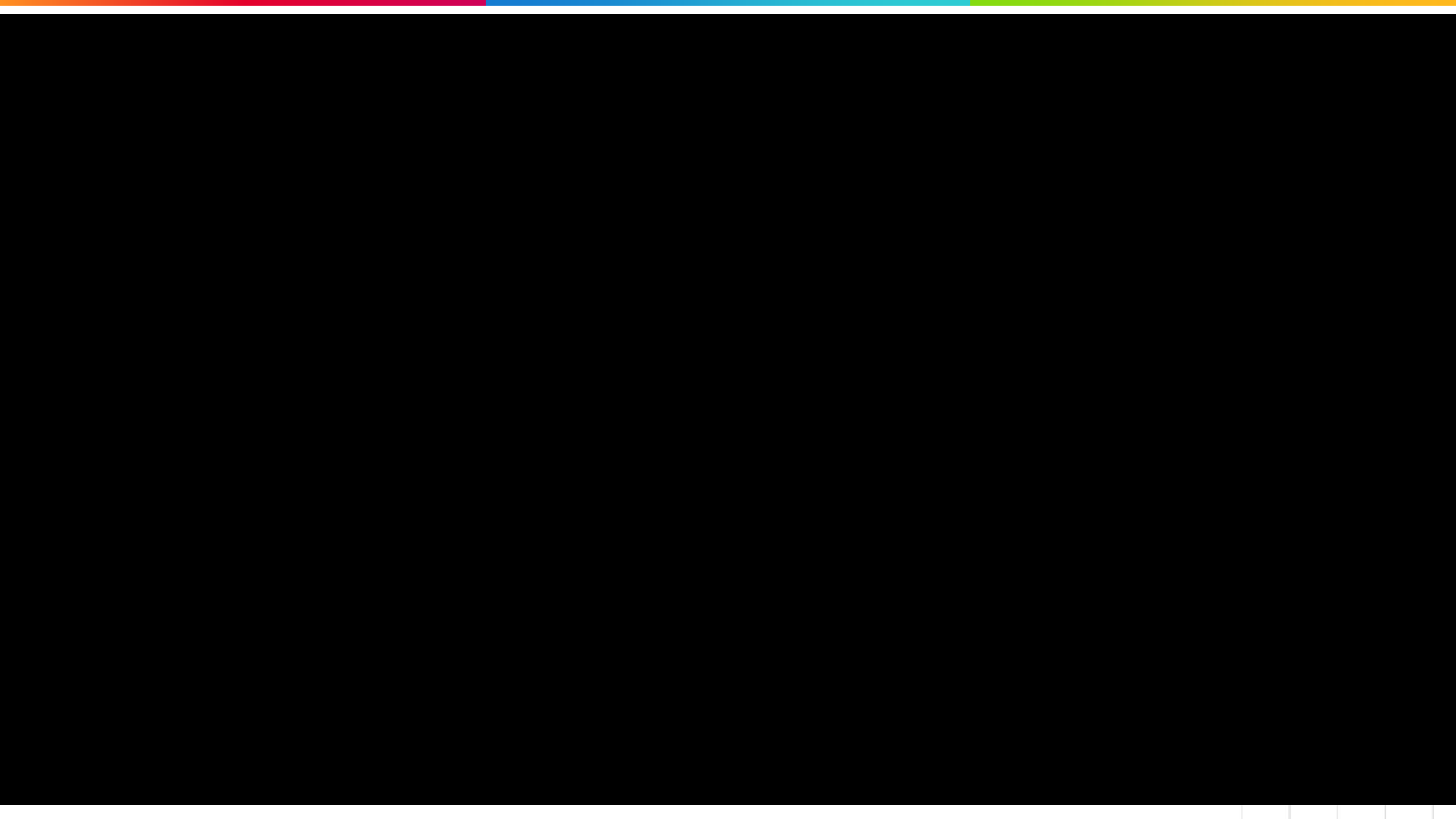
Cutouts

Component Placement

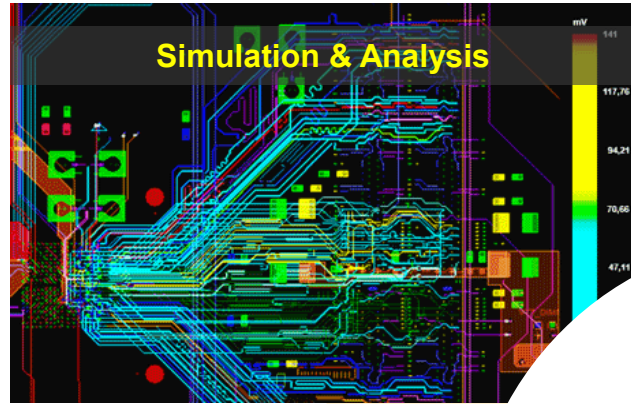
Rooms



- Final clearance checks
- Stress & thermal integrity
- Physical verification
- Mechanical manufacturing
- Design Assistant AI



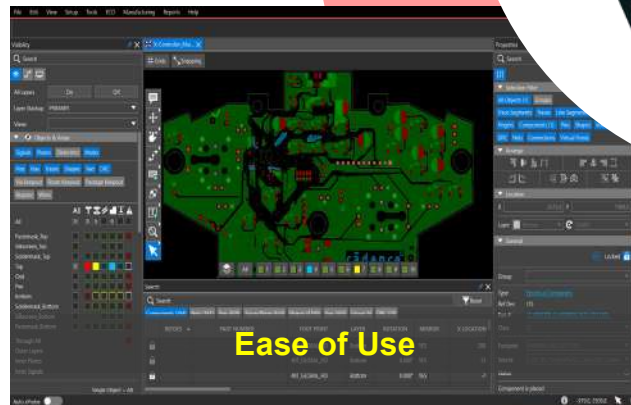
OrCAD X - Complete PCB Product Development Solution



Supply Chain



Mechanical Design





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